

# MATERIAL DECLARATION SHEET



Package Type	PTVS1-240C-M					
Product Line	Semiconductor Products					
Compliance Date	16 <sup>th</sup> July 2024					
RoHS Compliant	Yes	Terminal	e3	MSL	1	

No.	Construction Element (subpart)	Homogeneous Material	Material weight [g]	Homogeneous Material\ Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)
1	Encapsulation	Epoxy resin	2.1416	Amorphous Silica	60676-86-0	91.324	51.666	56.575
				Solid Epoxy Resin 1	Proprietary	3.036	1.718	
				Solid Epoxy Resin 2	Proprietary	2.655	1.502	
				Phenol Resin	Proprietary	2.703	1.529	
				Carbon Black	1333-86-4	0.282	0.16	
2	Electrodes	Copper Alloy	0.6469	Copper	7440-50-8	95.092	16.2506	17.090
				Silver	7440-22-4	4.893	0.836	
				Iron	7439-89-6	0.005	0.0009	
				Lead	7439-92-1	0.005	0.0009	
				Zinc	7440-66-6	0.003	0.0005	
				Phosphorus	7723-14-0	0.002	0.0003	
3	Leadframe	Copper Alloy	0.5804	Copper	7440-50-8	97.183	14.973	15.333
				Iron	7439-89-6	2.600	0.352	
				Phosphorus	7723-14-0	0.200	0.006	
				Zinc	7440-66-6	0.012	0.001	
				Lead	7439-92-1	0.005	0.001	
4	Chip	Silicon	0.1459	Silicon	7440-21-3	89.399	3.446	3.854
				Nickel	7440-02-0	5.902	0.227	
				Aluminum	7429-90-5	4.273	0.165	
				Gold	7440-57-5	0.426	0.016	
5	Solder Paste	Solder	0.1293	Lead	7439-92-1	92.500	3.2234	3.416
				Tin	7440-31-5	5.000	0.1123	
				Silver	7440-22-4	2.500	0.0806	
6	Clip	Copper Alloy	0.1224	Copper	7440-50-8	95.092	3.0747	3.233
				Silver	7440-22-4	4.893	0.1582	
				Iron	7439-89-6	0.005	0.0002	
				Lead	7439-92-1	0.005	0.0002	
				Zinc	7440-66-6	0.003	0.0001	
7	Terminal Finish	Tin	0.0189	Phosphorous	7723-14-0	0.002	0.0001	0.499
		Total weight	3.7854	Tin	7440-31-5	100.000	0.499	

\* 7(a) Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)